



Genesis 2000 Version 9.5

With Expanded Functionality

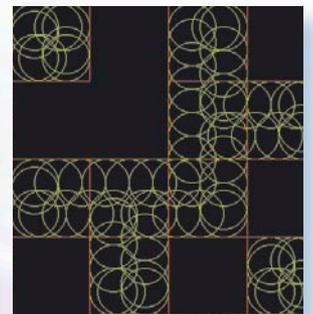
Genesis 2000 v9.5 with Expanded Functionality

Genesis 2000 v9.5 delivers new and enhanced editing tools to make job editing more secure. New options for input translation, analysis and DFM tools continue to boost yields and cut cycle time, while new netlist optimization functionality enables early-stage electrical testing.

Out-of-the-box functionality

Feature highlights:

- InLink – copies InPlan™ panelization data and drill sizes to CAM job
- New Editor functions:
 - Multi-Layer Copy – copies multiple layers from job/step at once
 - Move & Stretch
 - Offset Pad Edges
- Improved Feature filter:
 - ‘Or’ operator for attributes
 - Ranges for symbol names
 - Select text by text value
 - Select by layer/board net
- Convert features to laser drill pattern
- Netlist enhancements – supports rotated net points, designators in IPC-356A output and filters for layer netlist compare
- Netlist Optimizer – marks power/ground nets for capacitance test on flying probe testers
- Print layer enhancements:
 - Change layer order in separate mode
 - Change layer color in together mode

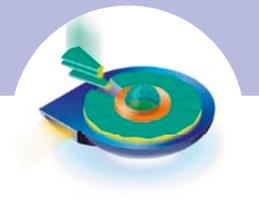


Convert feature to laser drill pattern

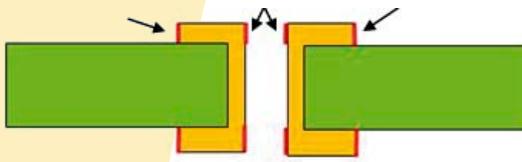


Multi-Layer Copy – copies multiple layers from job/step at once

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Extend/shorten slot length



Copper edge calculations

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- Extend/shorten slot length (Edit function, Drill Tool Manager)
- Improved copper area calculation:
 - Edge copper calculation
 - Copper area of both layers separately
 - Ignore PTH holes without pads
 - Calculate exposed area with multiple mask layers
 - Define percentage precision
 - Save distribution map as JPG picture
- Improved graphic compare
- Improved DXF file input:
 - Supports TTF fonts
 - Converts outlines to surface
- Automatic re-input of RS274X with new configuration parameter value in case of warning
- Auto Drill Manager
 - Table-wide tool sorting in NC table
 - Splits slot tools by length in drill table
 - Adds slot pilot holes
 - Supports Excellon R-command in output
- New Sliver Repair DFM – contains all current sliver actions with algorithm enhancements. New report mode for reporting problems without repairing them.
- Enhanced DFM and analysis actions:
 - Solder Mask, Silk Screen, Signal Layer and Drill Checks
 - Solder Mask Repair
 - Galvanic Etch Compensation
 - Power/Ground Analysis
 - Advanced Teardrop Creation
 - Redundant Line Removal

New Options for Genesis 2000 v9.5

- **Critical Via Checks**
Run Critical Via Checks to identify and create marks (on a separate mark layer) and critical vias. Critical vias are vias that, when missing, create an open in the electrical net.
- **Subassembly Netlist Optimization**
Create and output an optimized netlist for a defined subassembly, without changing the matrix and before the final assembly.
- **Plating Mask Checks**
Check that plating mask clearances do not exceed one board net on the related outer layers. View reports comparing spacing and annular ring measurements on the plating mask with outer layer copper measurements.
- **Scale per Step in OPFX Output**
Assign different scaling to different step locations on the panel, when outputting layers to Orbotech plotters.